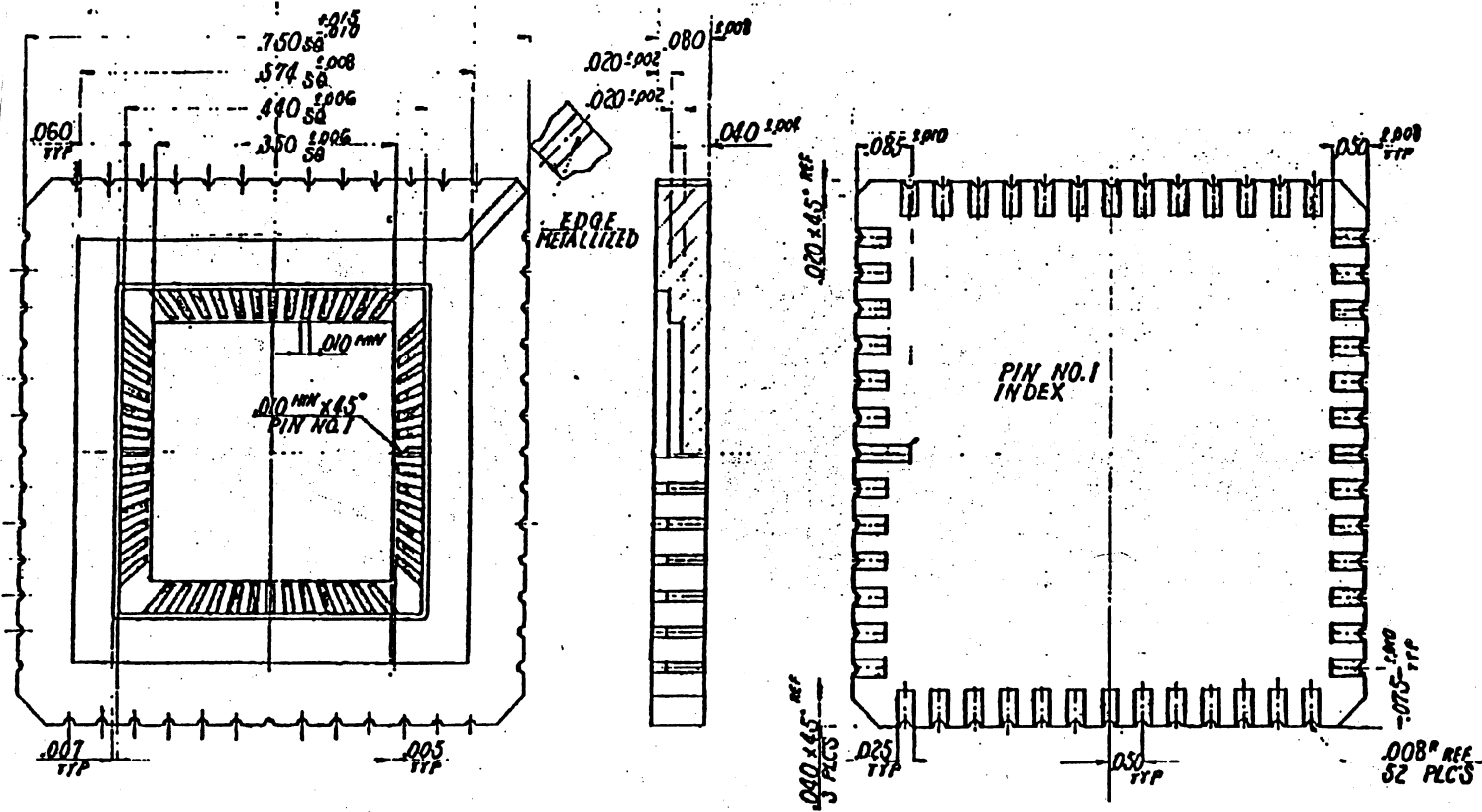


SSM P/N LCC05204



NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

NAME 52 LEAD CHIP CARRIER				TOLERANCES: UNLESS OTHERWISE SPECIFIED ± 1% NIL ± .005		DRAWN CHECKED APPROVED DATE	
DRAWN 8/1				MATERIAL A-440		DATE 77-8-10	
A ADD: SHEET NO. 2/2				DATE		PAGE NO. PB-92155-A	
CHANGE				DATE		DRAWN	

